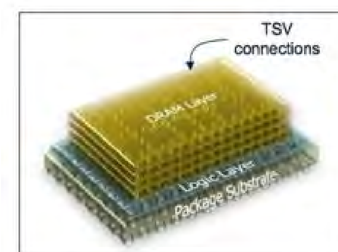
Denali Memory Report

It's Official: Microsoft joins 3D Hybrid Memory Cube Consortium with Micron, Samsung, Altera, IBM, Open-Silicon, and Xilinx

Posted on May 14, 2012

Last week, the Hybrid Memory Cube Consortium announced that Microsoft had joined Micron, Samsung, Altera, IBM, Open-Silicon, and Xilinx in the development of high-performance 3D SDRAM subsystems based on the Hybrid Memory Cube.



For more information on the Hybrid Memory Cube, see:

- 3D Thursday: Hybrid Memory Cube—wide I/O only more so—gets an industry consortium
- Want to know more about the Micron Hybrid Memory Cube (HMC)? How about its terabit/sec data rate?
- 3D Thursday: Micron's 3D Hybrid Memory Cube delivers more DRAM bandwidth at lower power and in a smaller form factor using TSVs
- Is 2012 going to be another breakout year for NAND Flash and Low-Power Design?
- 3D Thursday: Micron to present Hybrid Memory Cube status at EDPS in Monterey, April 6—there's a lot of news

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